



IPSR INTERNATIONAL LAUNCH
 Wednesday, November 28th, 2018
 MIT, Samberg Conference Center, Cambridge, MA

IPSR-International brings together the EU, US and Asian Roadmap efforts under a single governance and reporting structure. Members of Technical Working Groups (TWGs) from these constituencies will meet on Wednesday, November 28th to formally merge their TWGs and documents. The initial structure for the global governance of the organization will be formulated at the end of the day.

8:00 Registration and Coffee

Session 1: Introduction to IPSR-International Roadmapping

9:00 Welcome and Introduction to the IPSR International Roadmapping Process

Robert C. Pfahl, Director, Integrated Photonic Systems Roadmap (IPSR) International

9:15 Objectives and Outcomes

Peter van Arkel, Berenschot International

Session 2: Technology Working Group (TWG) Breakout Meetings

9:30 (*all registrants will receive preparation materials prior to the meeting)

IPSR-I TWGS	Leaders
Heterogeneous Integration on Silicon:	Lionel Kimerling, MIT; Ajey Jacob, Global Foundries; Roel Baets, Ghent
Indium Phosphide and 3-5 Compounds:	Meint Smit, TU Eindhoven
Electronic-Photonic Packaging:	Peter O'Brien, Tyndall
Electronic-Photonic Interconnect:	Terry Smith, 3M
Electronic-Photonic Connectors:	John MacWilliams, US Competitors
Electronic-Photonic Assembly:	Dick Otte, Promex Industries; Yi Qian, MRSI Systems
Electronic-Photonic Test:	Tom Brown, AIM Photonics; Dave Armstrong, Advantest; Sylwester Latkowski, Eindhoven
Integrated Photonic Sensors:	Ben Miller, U of Rochester; Anu Agarwal, MIT
Electronic-Photonic Design Automation:	Twan Korthorst, Synopsis

12:00 Attendee Lunch

Session 3: Cross Cutting Issues

Track A: Interconnect 2035

Session Chair: Lionel Kimerling, MIT

1:00 Keynote Presentation: Future Evolution of Interconnect

John MacWilliams, US Competitors

1:45 Panel Discussion

Peter O'Brien, Tyndall; Terry Smith, 3M; Dick Otte, Promex Industries; Sylwester Latkowski, Eindhoven

Track B: Cross Cutting Device Technology Needs Discussion

Session Chair: Meint Smit

**1:00 Heterogenous Integration on Silicon TWG
 Indium Phosphide and 3-5 Compounds TWG
 Electronic-Photonic Design Automation TWG**

2:30 Break

Session 4: Component Technology for Future Roadmaps

Tracks A and B

3:00 **Working Discussion on Interconnect Priorities During the Next Decade**

Objective: Define trade-offs that will govern solutions to key technology gaps

Session Chair: Terry Smith, 3M

4:00 **Workshop Summary**

Ton Backx, Photon Delta and Lionel Kimerling, MIT

4:30 **Adjourn**